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## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

## FAST RECOVERY RECTIFIER DIODES

PRELIMINARY DATASHHET

### MAIN PRODUCT CHARACTERISTICS

$I_{F(AV)}$	2 x 30 A
$V_{RRM}$	400 V
$T_j$ (max)	150°C
$V_F$ (max)	1.3 V

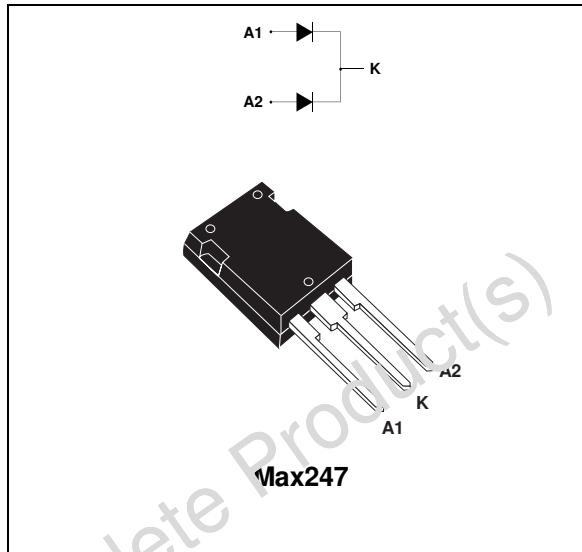
### FEATURES AND BENEFITS

- VERY LOW REVERSE RECOVERY TIME
- VERY LOW SWITCHING LOSSES
- LOW NOISE TURN-OFF SWITCHING

### DESCRIPTION

Dual 400V rectifiers suited for Switch Mode Power Supplies and other converters.

Packaged in Max247, this device is also intended for use in welding equipment and telecom power supplies.



### ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter			Value	Unit		
$V_{RRM}$	Repetitive peak reverse voltage			400	V		
$I_{FRM}$	Repetitive peak forward current	$t_p = 5 \mu s$ F=5kHz		380	A		
$I_{F(RMS)}$	RMS forward current			50	A		
$I_{(Ave)}$	Average forward current	$T_c = 105^\circ C$ $\delta = 0.5$	Per diode	30	A		
			Per device	60			
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10 ms$ Sinusoidal		300	A		
$T_{stg}$	Storage temperature range			- 55 to + 150	°C		
$T_j$	Maximum operating junction temperature			150	°C		

## BYT230Y-400

### THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
$R_{th(j-c)}$	Junction to case	Per diode Total	0.95 0.55 °C/W
		Coupling	0.15 °C/W

When the diodes 1 and 2 are used simultaneously :  
 $\Delta T_j(\text{diode 1}) = P(\text{diode 1}) \times R_{th(j-c)}(\text{Per diode}) + P(\text{diode 2}) \times R_{th(c)}$

### STATIC ELECTRICAL CHARACTERISTICS (per diode)

Symbol	Parameter	Tests Conditions		Min.	Typ.	Max.	Unit
$I_R$ *	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			35	$\mu\text{A}$
		$T_j = 125^\circ\text{C}$			3	12	$\text{mA}$
$V_F$ **	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 30 \text{ A}$			1.5	V
		$T_j = 125^\circ\text{C}$	$I_F = 30 \text{ A}$		0.9	1.3	
		$T_j = 25^\circ\text{C}$	$I_F = 60 \text{ A}$			1.7	
		$T_j = 125^\circ\text{C}$	$I_F = 60 \text{ A}$		1.1	1.6	

Pulse test : \*  $t_p = 5 \text{ ms}, \delta < 2\%$

\*\*  $t_p = 380 \mu\text{s}, \delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 1.0 \times I_F(AV) + 0.01 I_F^2(\text{RMS})$$

### RECOVERY CHARACTERISTICS

Symbol	Test Conditions			Min.	Typ.	Max.	Unit
$t_{rr}$	$T_j = 25^\circ\text{C}$	$I_F = 0.5 \text{ A}$	$I_R = 1 \text{ A}$	$I_{rr} = 0.25 \text{ A}$		50	ns
		$I_F = 1 \text{ A}$	$V_R = 30 \text{ V}$	$dI_F/dt = -15 \text{ A}/\mu\text{s}$		100	

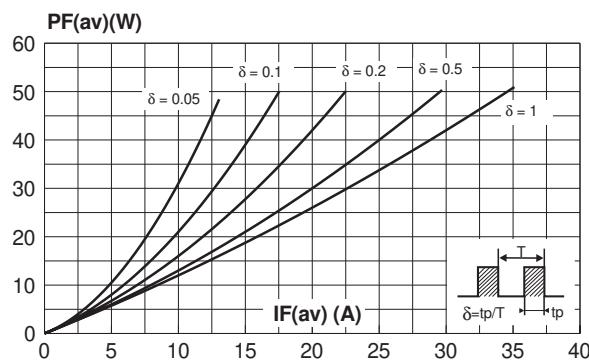
### TURN-OFF SWITCHING CHARACTERISTICS (without serie inductance)

Symbol	Test Conditions			Min.	Typ.	Max.	Unit
$t_{IRM}$	$dI_F/dt = -120 \text{ A}/\mu\text{s}$	$V_{CC} = 200 \text{ V}$ $I_F = 30 \text{ A}$ $L_p = 0.05 \mu\text{H}$ $T_j = 100^\circ\text{C}$				75	ns
	$dI_F/dt = -240 \text{ A}/\mu\text{s}$				50		
$I_{IRM}$	$dI_F/dt = -120 \text{ A}/\mu\text{s}$	$L_p = 0.05 \mu\text{H}$ $T_j = 100^\circ\text{C}$				9	A
	$dI_F/dt = -240 \text{ A}/\mu\text{s}$				12		

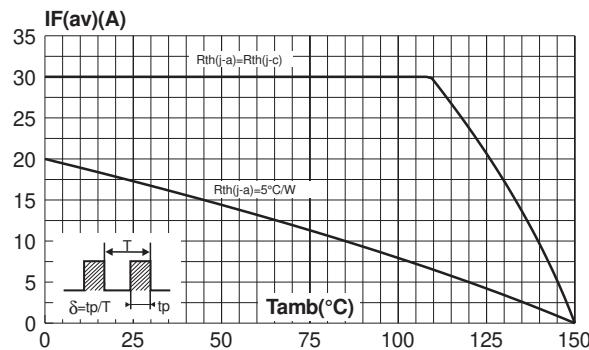
### TURN-OFF OVERVOLTAGE CORFFICIENT (with serie inductance)

Symbol	Test Conditions			Min.	Typ.	Max.	Unit
$C = \frac{V_{RP}}{V_{CC}}$	$T_j = 100^\circ\text{C}$	$V_{CC} = 60 \text{ V}$	$I_F = I_F(AV)$		3.3		/

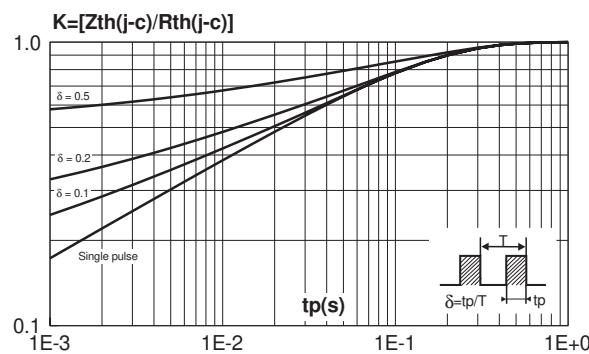
**Fig. 1:** Average forward power dissipation versus average forward current (per diode).



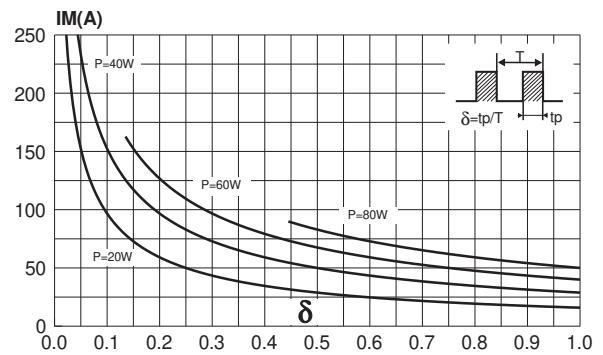
**Fig. 3:** Average forward current versus ambient temperature ( $\delta=0.5$ , per diode).



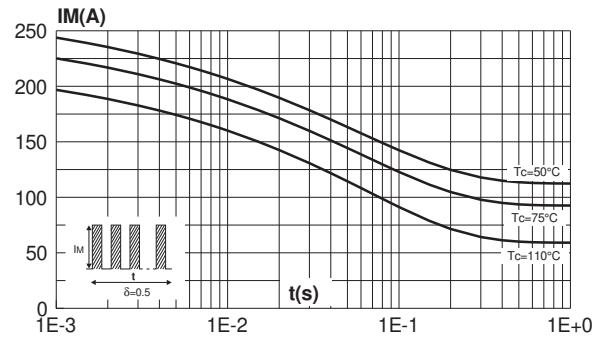
**Fig. 5:** Relative variation of thermal impedance junction to case versus pulse duration (per diode).



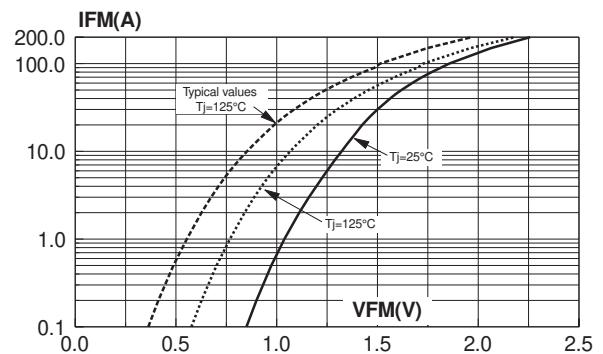
**Fig. 2:** Peak current versus form factor (per diode).



**Fig. 4:** Non repetitive surge peak forward current versus overload duration (per diode).

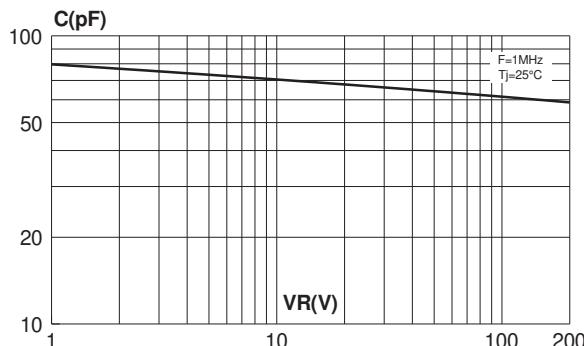


**Fig. 6:** Forward voltage drop versus forward current (maximum values, per diode).

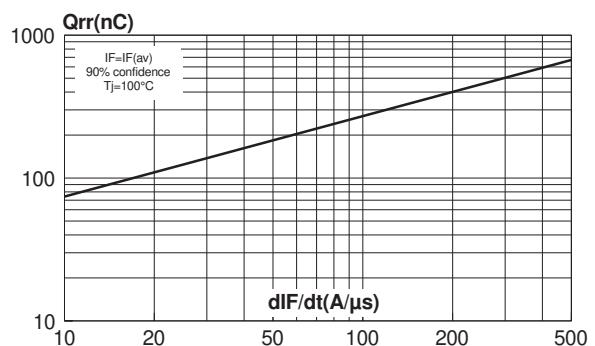


## BYT230Y-400

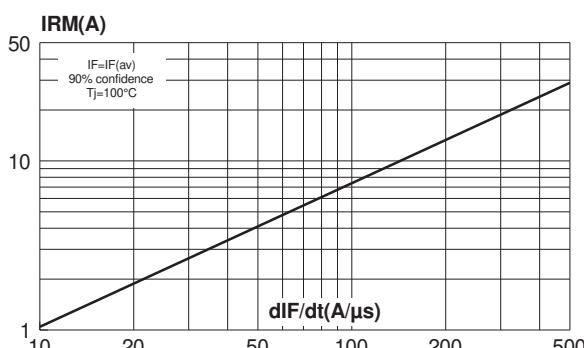
**Fig. 7:** Junction capacitance versus reverse voltage applied (typical values, per diode).



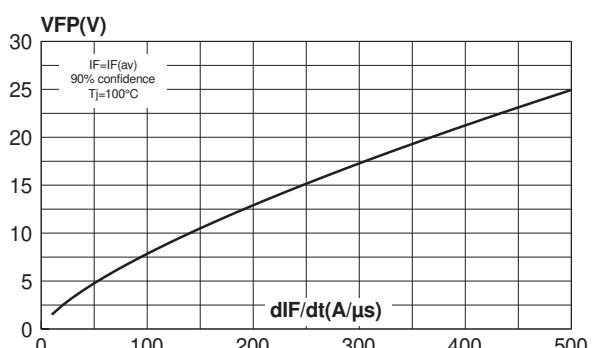
**Fig. 8:** Recovery charges versus  $dI_F/dt$  (per diode).



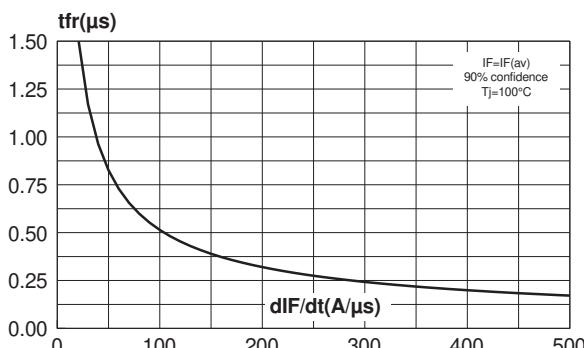
**Fig. 9:** Recovery current versus  $dI_F/dt$  (per diode).



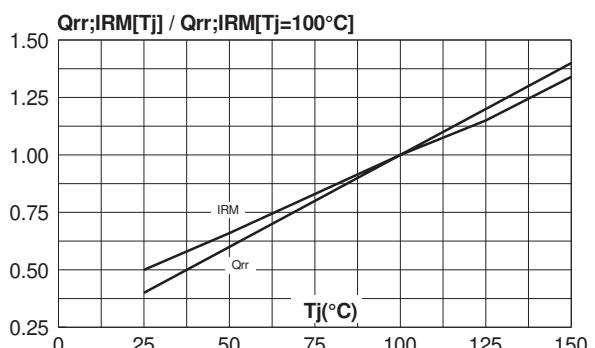
**Fig. 10:** Transient peak forward versus  $dI_F/dt$  (per diode).



**Fig. 11:** Forward recovery time versus  $dI_F/dt$  (per diode).

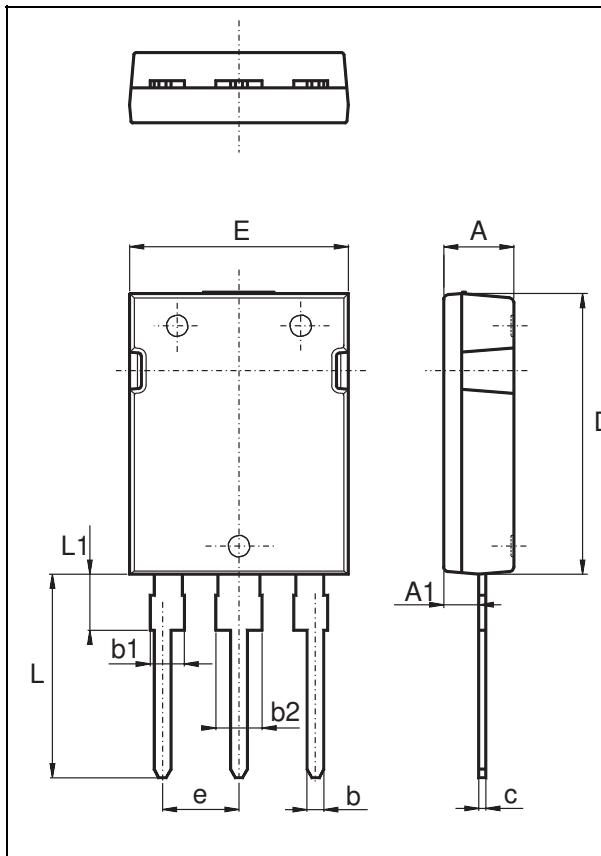


**Fig. 12:** Dynamic parameters versus junction temperature.



## PACKAGE MECHANICAL DATA

Max247



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.70	5.30	0.185	0.209
A1	2.20	2.60	0.087	0.102
b	1.00	1.40	0.038	0.055
b1	2.00	2.40	0.079	0.094
b2	3.00	3.40	0.118	0.133
c	0.40	0.80	0.016	0.031
D	19.70	10.30	0.776	0.799
e	5.35	5.55	0.211	0.219
E	15.30	15.90	0.602	0.626
L	14.20	15.20	0.559	0.598
L1	3.70	4.30	0.146	0.169

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
BYT230Y-400	BYT230Y-400	Max247	5 g.	30	Tube

■ Epoxy meets UL94,V0

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